



Product/Process Change Notice - PCN 18_0097 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: ADRF6821 Process Robustness Improvement and Die Revision

Publication Date: 03-Jul-2018

Effectivity Date: 05-Oct-2018 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Revised "description of change" for further clarification from "Added Down-Bond to ESD ground connections; Back-to-Back diodes" to "Added Back-to-Back diodes on down-bond pads."

Description Of Change:

1. Die Revision:

- Added ESD Domain connections between all grounds; Back-to-Back diodes
- Added Back-to-Back diodes on Down-Bond pads.
- Added up/down diodes between interconnected blocks.

2. Electrical Specification:

- Device Identification through Register Readback is change:
- ADI Engineering Register 0x0010 value from 0x20 to 0x30
- ADI Engineering Register 0x1010 value from 0x20 to 0x34

Reason For Change:

1. Process Robustness Improvement.
2. Increased production to meet customers demand.

Impact of the change (positive or negative) on fit, form, function & reliability:

- No change to fit, form, function & reliability.

Product Identification *(this section will describe how to identify the changed material)*

Device Identification through Register Readback.

Summary of Supporting Information:

Qualification will be performed per Industry Standard Test Methods. See attached Qualification Plan.

Supporting Documents

Attachment 1: Type: Qualification Plan

ADI_PCN_18_0097_Rev_A_ADRF6821_Qualification_Plan.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:

PCN_Americas@analog.com

Europe:

PCN_Europe@analog.com

Japan:

PCN_Japan@analog.com

Rest of Asia:

PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Existing Parts - Product Family / Model Number (3)				
ADRF6821 / ADRF6821ACPZ	ADRF6821 / ADRF6821ACPZ-RL7	ADRF6821 / ADRF6821XCPZ		

Appendix B - Revision History			
Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	20-Jun-2018	22-Sep-2018	Initial Release.
Rev. A	03-Jul-2018	05-Oct-2018	Revised "description of change" for further clarification from "Added Down-Bond to ESD ground connections; Back-to-Back diodes" to "Added Back-to-Back diodes on down-bond pads."

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